



Dk 3.4*
@2GHz

CTE z-axis
37ppm/°C

Tg(DMA) 200°C

* Resin content 70wt%

Applications
Mobile
Smartphone, Tablet PC, etc.



Halogen-free

Laminate

R-A555W R-A555Y

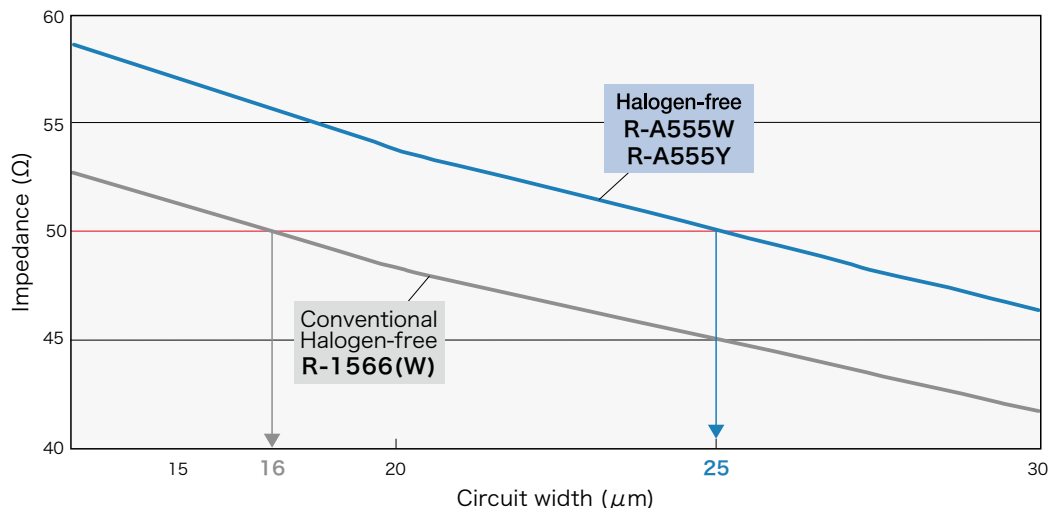
Prepreg

R-A550W R-A550Y

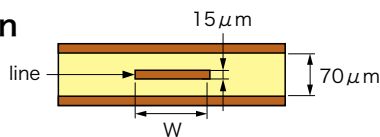
**Low Dk Halogen-free
multi-layer circuit board materials**

Good impedance matching at ultra-thin insulated layer with low Dk property. Contribute to thinner and compact of mobile product.

Impedance simulation (Strip Line)



Construction



General properties

Item		Test method	Condition	Unit	Halogen-free R-A555W R-A555Y	Conventional Halogen-free R-1566(W)
Glass transition temp. (Tg)		DMA	A	℃	200	170
CTE z-axis	α 1	IPC-TM-650 2.4.24	A	ppm/℃	37	40
	α 2				210	180
T288(with copper)		IPC-TM-650 2.4.24.1	A	min	>60	3
Dielectric constant(Dk)*1	2GHz	IPC-TM-650 2.5.5.5	C-24/23/50	—	3.4	—
Dissipation factor(Df)*1					0.010	—

The sample thickness is 0.8mm.

*1 Resin content 70wt%

[Please see our website for Notes before you use.](#)

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry R-A555W 

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